

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------|------------------|---------|------------------|
| L1 | 1341 | (257/686 or 257/687).ccls. and @ad<"20030222" and (soft or flexible or elastic or elastomer or epoxy) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/05/30 11:35 |
| L2 | 1341 | (257/686 or 257/687).ccls. and @ad<"20030222" and (soft or flexible or elastic or elastomer or epoxy) | US-PGPUB; USPAT; EPO; JPO; DERWENT | OR | ON | 2006/05/30 11:39 |
| L3 | 670 | (257/723).ccls. and @ad<"20030222" and (soft or flexible or elastic or elastomer or epoxy) not L2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/05/30 11:39 |
| L4 | 315 | (257/787-793).ccls. and @ad<"20030222" and ((soft or flexible or elastic or elastomer or epoxy) with side) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/05/30 11:49 |
| L5 | 390 | semiconductor and (chip or die or substrate) and (package or assembly or housing or module) and @ad<"20030222" and (encapsul\$5) and ((soft or flexible or elastic) same (filler)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/05/30 12:01 |